isola

Semi-Flex
multi-family semi-flexible cores and prepregs
Semi-Flex Introduction

The Semi-Flex family of laminates and prepregs are a low cost alternative for flex-to-install technology applications where non-dynamic or limited bending is required.
Semi-Flex Value Proposition

- Low cost of ownership
- Conventional PCB processing
- Dimensional Stability through reinforced E-glass
- Lead-free compatible
- Manufactured in Europe
- No additional UL requirements
- Available across a wide range of Isola products
Semi-Flex - Availability

- Material thickness 60um, 80um, 100um
- Glass Styles 106, 1080, 2116
- HD Copper 18um, 35um
- Product DE104, IS400, IS410, 370HR, 408HR
- Available in sheets, panels or rolls
Semi-Flex - Performance

- Test Matrix:
  - Material: IS400, IS410, 408HR, 370HR
  - Glass Styles: 106, 1080 and 2116 (single ply)
  - Copper Foil: 18um HD copper
  - Bending Radius: 2mm, 3mm
  - Bending Angle: 180°degrees
  - Track Width: 300um
Semi-Flex - Performance

Test fixture and test set up:

Failure criteria: Break in the track after \( n \) bending cycles
Semi-Flex – Test Results

IS400, Number of bends, bending angle 180°

* Prediction based on pilot tests, extensive test series will soon be completed.
Semi-Flex – Test Results

IS410, Number of bends, bending angle 180°

* Prediction based on pilot tests, extensive test series will soon be completed.
Semi-Flex – Test Results

408HR, Number of bends, bending angle 180°

* Prediction based on pilot tests, extensive test series will soon be completed.
Semi-Flex – Test Results

370HR, Number of bends, bending angle 180°

* Prediction based on pilot tests, extensive test series will soon be completed.
Semi-Flex Summary

- Single ply constructions using HD copper give excellent performance characteristics (>100 bends)
- More testing planned for multiple ply constructions with results due in Q1 2012
- Cost and performance benefits versus traditional flex circuit materials such as PET, PEN and polyimide
- Conventional PCB processing and known design aspects of reinforced substrates